Level Translating I2C Bus/SMBus Repeater

Features

- 2 channel, bidirectional buffer
- I^2C-bus and SMBus compatible
- Port A operating voltage range : 0.8 V to 5.5 V
- Port B operating voltage range: 2.2 V to 5.5 V
- Voltage level translation from 0.8 V to 5.5 V and from 2.2 V to 5.5 V
- Active HIGH repeater enable input
- Open-drain input/outputs
- Lock-up free operation
- Supports arbitration and clock stretching across the repeater
- Accommodates Standard-mode and Fast-mode I^2C-bus devices and multiple masters
- Powered-off high-impedance I^2C-bus pins
- 5.5 V tolerant I^2C-bus and enable pins
- 0 Hz to 400 kHz clock frequency (the maximum system operating frequency may be less than 400 kHz because of the delays added by the repeater)
- ESD protection exceeds 8000V HBM per JESD22-A114
- Packages offered: MSOP-8L , TDFN-8 2*3-8L

Description

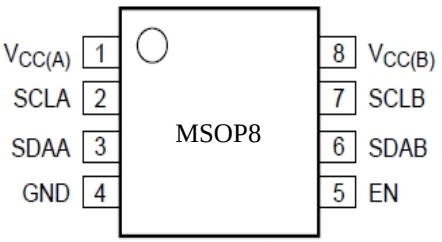
The PI6ULS5V9517B is a CMOS integrated circuit intended for I^2C-bus or SMBus applications. It can provide level shifting between low voltage (down to 0.8 V) and higher voltage (2.2 V to 5.5 V) in mixed-mode applications. And it enables I^2C and similar bus system to be extended ,without degradation of performance even during level shifting.

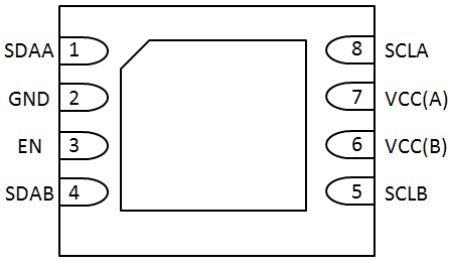
The PI6ULS5V9517B enables the system designer to isolate two halves of a bus for both voltage and capacitance, accommodating more I2C devices or longer trace length. It also permits extension of the I^2C-bus by providing bidirectional buffering for both the data (SDA) and the clock (SCL) lines, thus allowing two buses of 400 pF to be connected in an I^2C application.

Pin Description

MSOP-8	TDFN2x3-8	Name	Description
1	7	V_{CCA}	port A supply voltage (0.8 V to 5.5 V)
2	8	SCLA	serial clock port A bus
3	1	SDAA	serial data port A bus
4	2	GND	supply ground (0 V)
5	3	EN	active HIGH repeater enable input
6	4	SDAB	serial data port B bus
7	5	SCLB	serial clock port B bus
8	6	V_{CCB}	port B supply voltage (2.2 V to 5.5 V)

Pin Configuration





TDFN2x3-8

Block Diagram

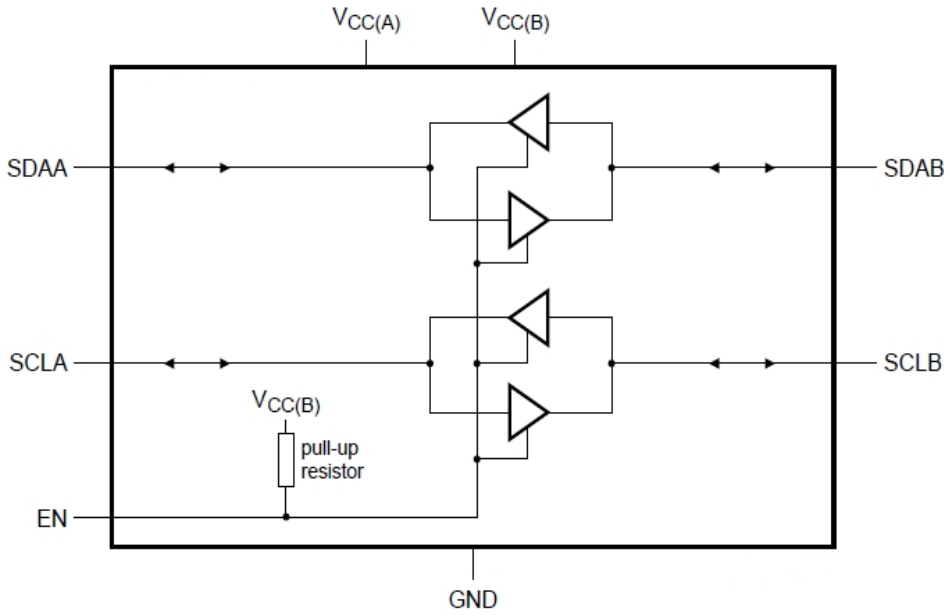


Figure 1:Block Diagram

EN	Function
H	SCLA = SCLB; SDAA = SDAB;
L	disabled

Maximum Ratings

Supply Voltage port B .....–0.5V to +7V
Supply Voltage port A .....–0.5V to +7V
DC Input Voltage ..... –0.5V to +7V
Control Input Voltage (EN) .....–0.5V to+7V
Total power dissipation(1).....100mW
Input/output current(port A&B).....50mA
Input current(EN,VCCA,VCCB,GND).....50mA
ESD: HBM Mode.....8000V
Storage Temperature .....–55℃ to +125℃

Note:

1. Stresses greater than those listed under MAXIMUMRATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability

Recommended Operating Conditions

V_{CC} = 2.2 V to 5.5 V; GND = 0 V; T_{amb}= –40 °C to +85 °C; unless otherwise specified

Symbol	Parameter	CONDITIONS	Min.	TYP	Max.	Unit
Vcc(B)	supply voltage port B		2.2		5.5	V
Vcc(A)	supply voltage port A		0.8		5.5	V
ICC(A)	supply current on pin Vcc(A)				500	uA
ICCH	HIGH-level supply current	both channels HIGH;VCC = 5.5 V; SDAn = SCLn = VCC		0.5	2	mA
ICCL	LOW-level supply current	both channels LOW;VCC = 5.5 V; one SDA and one SCL = GND; other SDA and SCL open		0.5	2	mA
ICC(B)c	contention port B supply current	VCC = 5.5 V; SDAn = SCLn = VCC		0.5	2	mA

DC Electrical Characteristics

V_{CC} = 2.2 V to 5.5 V; GND = 0 V; T_{amb}= –40 °C to +85 °C; unless otherwise specified

Parameter	Description	Test Conditions[1]	Min	Typ.[2]	Max	Unit
Input and output SDAB and SCLB						
V_{IH}	HIGH-level input voltage		0.7$V_{CC(B)}$		5.5	V
V_{IL}[1]	LOW-level input voltage		-0.5		+0.3$V_{CC(B)}$	V
V_{ILc}	contention LOW-level input voltage		-0.5	0.4		V
V_{IK}	input clamping voltage	I_I = 18 mA			1.2	V
I_{LI}	input leakage current	V_I = 3.6 V			1	A
I_{IL}	LOW-level input current	SDA, SCL; V_I = 0.2 V		10		A
V_{OL}	LOW-level output voltage	I_{OL} = 100 A or 6 mA	0.47	0.52	0.6	V
V_{OL} V_{ILc}	difference between LOW-level output and LOW-level input voltage contention	guaranteed by design		70		mV
I_{LOH}	HIGH-level output leakage current	V_O = 3.6 V			10	A
C_{io}	input/output capacitance	V_I = 3 V or 0 V; V_{CC} = 3.3 V V_I = 3 V or 0 V; V_{CC} = 0 V		6		pF
Input and output SDAA and SCLA						
V_{IH}	HIGH-level input voltage		0.7$V_{CC(A)}$		5.5	V
V_{IL} [2]	LOW-level input voltage		-0.5		+0.3$V_{CC(A)}$	V
V_{IK}	input clamping voltage	I_I = 18 mA			1.2	V
I_{LI}	input leakage current	V_I = 3.6 V			1	A
I_{IL}	LOW-level input current	SDA, SCL; V_I = 0.2 V				A
V_{OL}	LOW-level output voltage	I_{OL} = 6 mA		0.1	0.2	V
I_{LOH}	HIGH-level output leakage current	V_O = 3.6 V			10	A
C_{io}	input/output capacitance	V_I = 3 V or 0 V; V_{CC} = 3.3 V V_I = 3 V or 0 V; V_{CC} = 0 V		6		pF
Enable						
V_{IH}	HIGH-level input voltage		0.7$V_{CC(B)}$		5.5	V
V_{IL}	LOW-level input voltage		-0.5		+0.3$V_{CC(B)}$	V
I_{IL}	LOW-level input current	V_I = 0.2 V, EN; V_{CC} = 3.6 V		-10	-30	A
I_{LI}	input leakage current	Vi=Vcc(B)	-1		+1	A
C_i	input capacitance	V_I = 3.0 V or 0 V		6		pF

NOTES:

1 V_{IL} specification is for the first LOW level seen by the SDAB/SCLB lines. V_{ILC} is for the second and subsequent LOW levels seen by the SDAB/SCLB lines.

2, V_{IL} for port A with envelope noise must be below 0.3Vcc(A) for stable performance.

Dynamic Characteristics

V_{CC} = 2.2 V to 5.5 V; GND = 0 V; T_{amb}= –40 °C to +85 °C; unless otherwise specified.[1][2]

Symbol	Parameter	condition	Min	Typ.	Max	Unit
t_{PLH}	LOW-to-HIGH propagation delay	B-side to A-side		169	255	ns
t_{PHL}	HIGH-to-LOW propagation delay	B-side to A-side Vcc(A) 2.7 V		68	110	ns
		B-side to A-side Vcc(A) 3 V		103	300	ns
t_{TLH}	LOW-to-HIGH transition time	A-side		50	60	ns
t_{THL}	HIGH-to-LOW transition time	A-side Vcc(A) 2.7 V		3	105	ns
		A-side Vcc(A) 3 V		25	175	ns
t_{PLH}	LOW-to-HIGH propagation delay	A-side to B-side		67	110	ns
t_{PHL}	HIGH-to-LOW propagation delay	A-side to B-side		118	230	ns
t_{TLH}	LOW-to-HIGH transition time	B-side		140	170	ns
t_{THL}	HIGH-to-LOW transition time	B-side		40	105	ns
t_{SU}	set-up time	EN HIGH before START condition	100			ns
t_H	hold time	EN HIGH after STOP condition	100			ns

Note:
[1] Times are specified with loads of 1.35 k pull-up resistance and 57 pF load capacitance on port B, and 167 pull-up resistance and 57 pF load capacitance on port A. Different load resistance and capacitance will alter the RC time constant, thereby changing the propagation delay and transition times.
[2] Pull-up voltages are Vcc(A) on port A and Vcc(B) on port B.
[3] Typical values were measured with Vcc(A) = 3.3 V at Tamb = 25 C, unless otherwise noted.

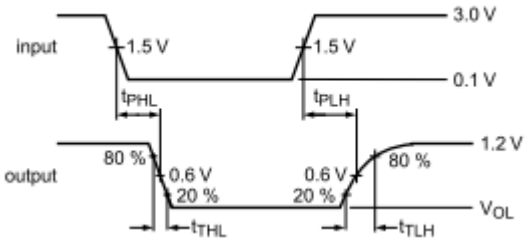


Figure 2: Propagation Delay and Transition Times B→A

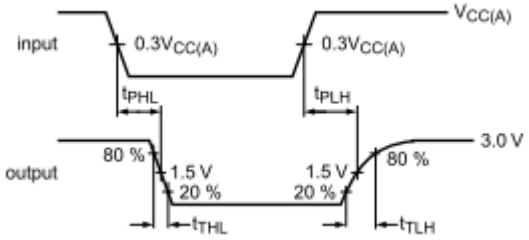


Figure 3: Propagation Delay and Transition Times A→B

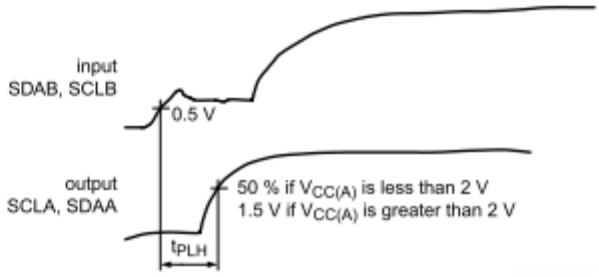
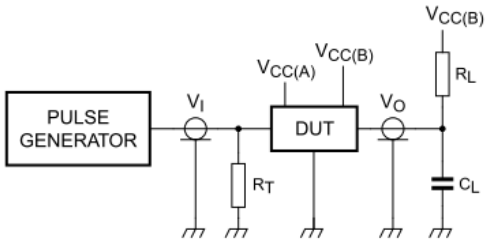


Figure4: Propagation Delay



RL = load resistor; 1.35 kΩ on port B; 167 Ω on port A (0.8 V to 2.7 V) and 450 Ω on port A (3.0 Vto 5.5 V).
CL = load capacitance includes jig and probe capacitance; 57 pF
RT = termination resistance should be equal to Z_0 of pulse generators

Figure 5:Test Circuit

Function Description

The B-side drivers operate from 2.2 V to 5.5 V. The output low level of port B internal buffer is approximately 0.5 V, while the input voltage must be 70mV lower (0.43V) or even more lower. The nearly 0.5V low signal is called a buffered low. When the B-side I/O is driven low internally, the low is not recognized as a low by the input. This feature prevents a lockup condition from occurring when the input low condition is released. This type of design on B port prevents it from being used in series with another PI6ULS5V9517B (B side) or similar devices ,because they don't recognize buffer low signals as a valid low .

The A-side drivers operate from 0.8 V to 5.5 V. The output low level of port A internal buffer is nearly 0V,while the input low level is set at 0.3Vcc(A) to accommodate the need for a lower LOW level in systems where the low voltage side supply voltage is as low as 0.8 V. Port A of two or more PI6ULS5V9517Bs can be connected together to allow a star topography with port A on the common bus. And port A can be connected directly to any other buffer with static or dynamic offset voltage. Multiple PI6ULS5V9517Bs can be connected in series, port A to port B, with no build-up in offset voltage with only time of flight delays to consider.

The EN pin can also be used to turn the drivers on and off. This can be used to isolate a badly behaved slave on power-up until after the system power-up reset. It should never change state during anI^2C-bus operation because disabling during a bus operation will hang the bus and enabling part way through a bus cycle could confuse the I^2C-bus parts being enabled. The enable pin should only change state when the global bus and the repeater port are in an idle state to prevent system failures.

After power-up and with the EN HIGH, a LOW level on port A (below 0.3Vcc(A)) turns the corresponding port B driver (either SDA or SCL) on and drives port B down to about 0.5 V. When port A rises above 0.3Vcc(A), the port B pull-down driver is turned off and the external pull-up resistor pulls the pin HIGH. When port B falls first and goes below 0.3Vcc(B) the port A driver is turned on and port A pulls down to 0 V. The port B pull-down is not enabled unless the port B voltage goes below 0.4 V. If the port B low voltage does not go below 0.5 V, the port A driver will turn off when port B voltage is above 0.7Vcc(B). If the port B low voltage goes below 0.4 V, the port B pull-down driver is enabled and port B will only be able to rise to 0.5 V until port A rises above 0.3Vcc(A).Then port B will continue to rise being pulled up by the external pull-up resistor. The Vcc(A) is only used to provide the 0.3Vcc(A) reference to the port A input comparators and for the power good detect circuit. The PI6ULS5V9517B logic and all I/Os are powered by the Vcc(B) pin.

As with the standard I2C system, pull-up resistors are required to provide the logic-high levels on the buffered bus. The PI6ULS5V9517B has standard open-collector configuration of the I2C bus. The size of these pull-up resistors depends on the system, but each side of the repeater must have a pull-up resistor. The device is designed to work with Standard mode and Fast mode I2C devices in addition to SMBus devices. Standard mode I2C devices only specify 3 mA in a generic I2C system, where Standard mode devices and multiple masters are possible. Under certain conditions, higher termination currents can be used.

Application Information

A typical application is shown in Figure 6. In this example, the system master is running on a 3.3 V I²C-bus while the slave is connected to a 1.2 V bus. Both buses run at 400 kHz. Master devices can be placed on either bus.

The PI6ULS5V9517B is 5-V tolerant, so it does not require any additional circuitry to translate between 0.8-V to 5.5-Vbus voltages and 2.2-V to 5.5-V bus voltages.

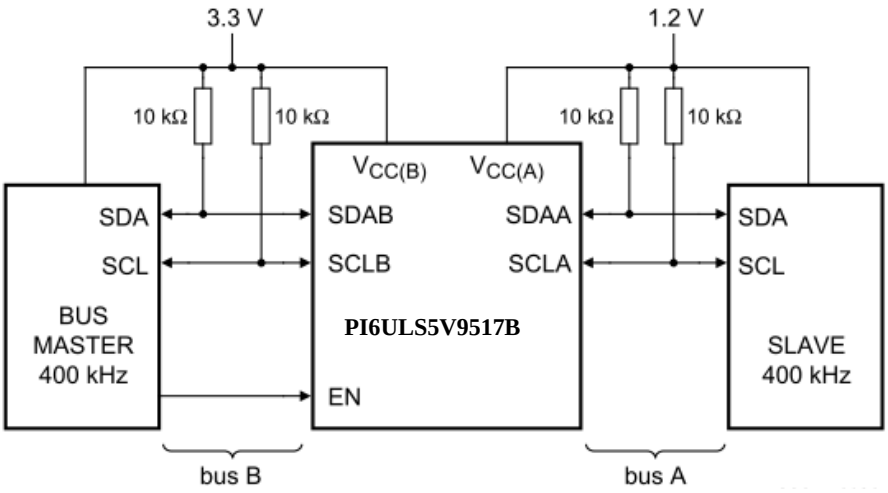


Figure 6:Typical Application

When port A of the PI6ULS5V9517B is pulled LOW by a driver on the I²C-bus, a comparator detects the falling edge when it goes below 0.3Vcc(A) and causes the internal driver on port B to turn on, causing port B to pull down to about 0.5 V. When port B of thePI6ULS5V9517B falls, first a CMOS hysteresis type input detects the falling edge and causes the internal driver on port A to turn on and pull the port A pin down to ground. In order to illustrate what would be seen in a typical application, refer to Figure 9 and Figure 10. If the bus master in Figure 6 were to write to the slave through the PI6ULS5V9517B, waveforms shown in Figure 9 would be observed on the A bus. This looks like a normal I²C-bustransmission except that the HIGH level may be as low as 0.8 V, and the turn on and turnoff of the acknowledge signals are slightly delayed.

On the B-side bus of the PI6ULS5V9517B, the clock and data lines would have a positive offset from ground equal to the VOL of the PI6ULS5V9517B. After the eighth clock pulse, the data line is pulled to the VOL of the slave device, which is very close to ground in this example. At the end of the acknowledge, the level rises only to the low level set by the driver in the PI6ULS5V9517B for a short delay, while the A-bus side rises above 0.3 Vcc(A) and then it continues high.

Multiple PI6ULS5V9517B port A sides can be connected in a star configuration (Figure 7),allowing all nodes to communicate with each other.

Multiple PI6ULS5V9517Bs can be connected in series (Figure 8) as long as port A is connected to port B. I²C-bus slave devices can be connected to any of the bus segments. The number of devices that can be connected in series is limited by repeater delay/time-of-flight considerations on the maximum bus speed requirements.

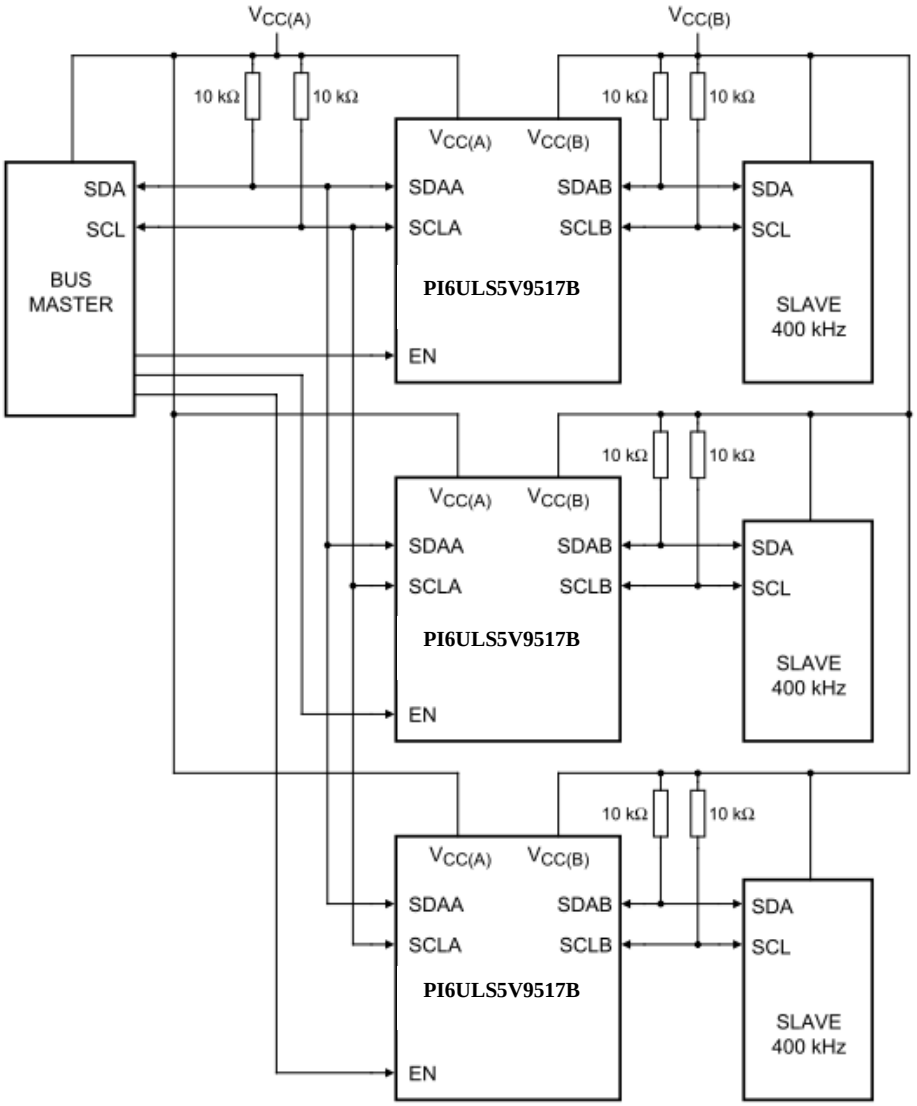


Figure 7:Typical Star Application

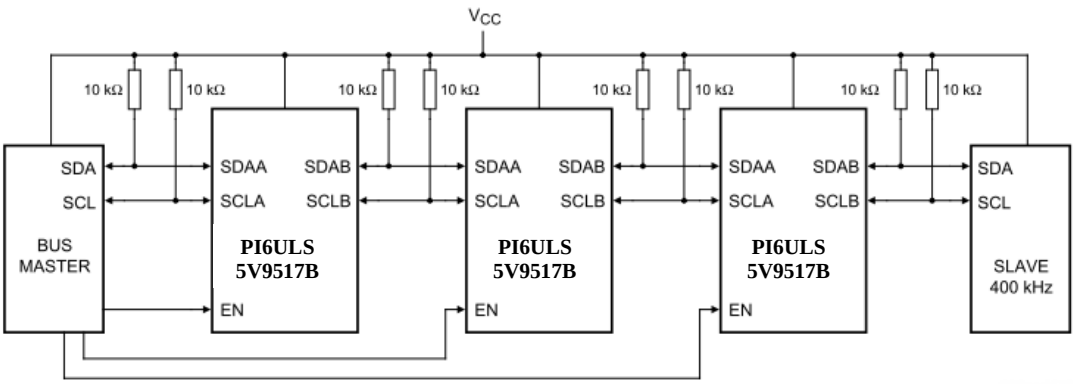


Figure 8:Typical Series Application

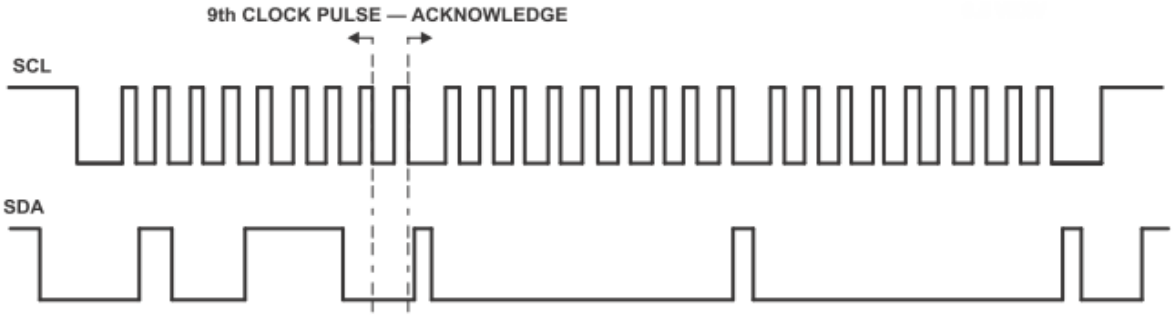


Figure 9:Bus A (0.8-V to 5.5-V Bus) Waveform

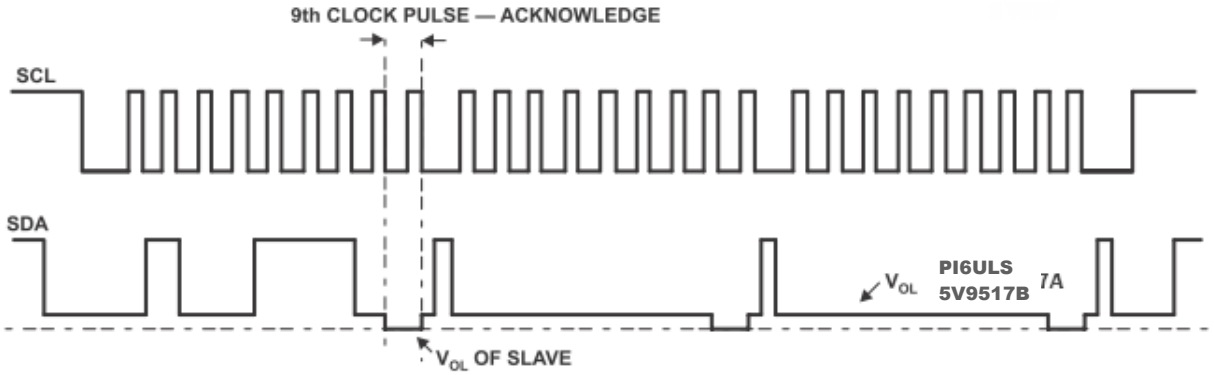


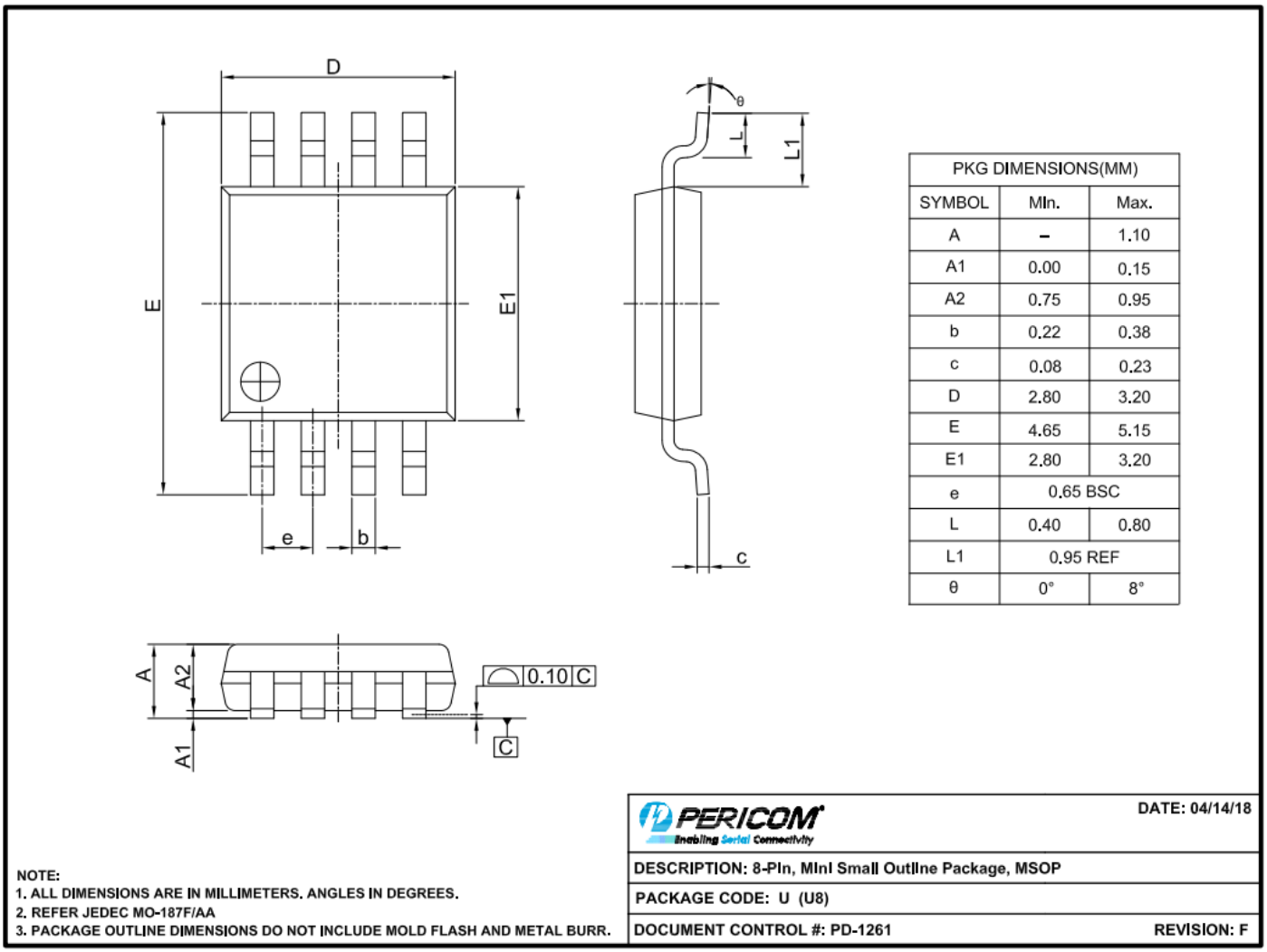
Figure 10: Bus B (2.2-V to 5.5-V Bus) Waveform

Part Marking

Top mark not available at this time. To obtain advance information regarding the top mark, please contact your local sales representative.

Packaging Mechanical

8-MSOP (U)



PKG DIMENSIONS(MM)		
SYMBOL	Min.	Max.
A	–	1.10
A1	0.00	0.15
A2	0.75	0.95
b	0.22	0.38
c	0.08	0.23
D	2.80	3.20
E	4.65	5.15
E1	2.80	3.20
e	0.65 BSC	
L	0.40	0.80
L1	0.95 REF	
θ	0°	8°

NOTE:
1. ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES IN DEGREES.
2. REFER JEDEC MO-187F/AA
3. PACKAGE OUTLINE DIMENSIONS DO NOT INCLUDE MOLD FLASH AND METAL BURR.

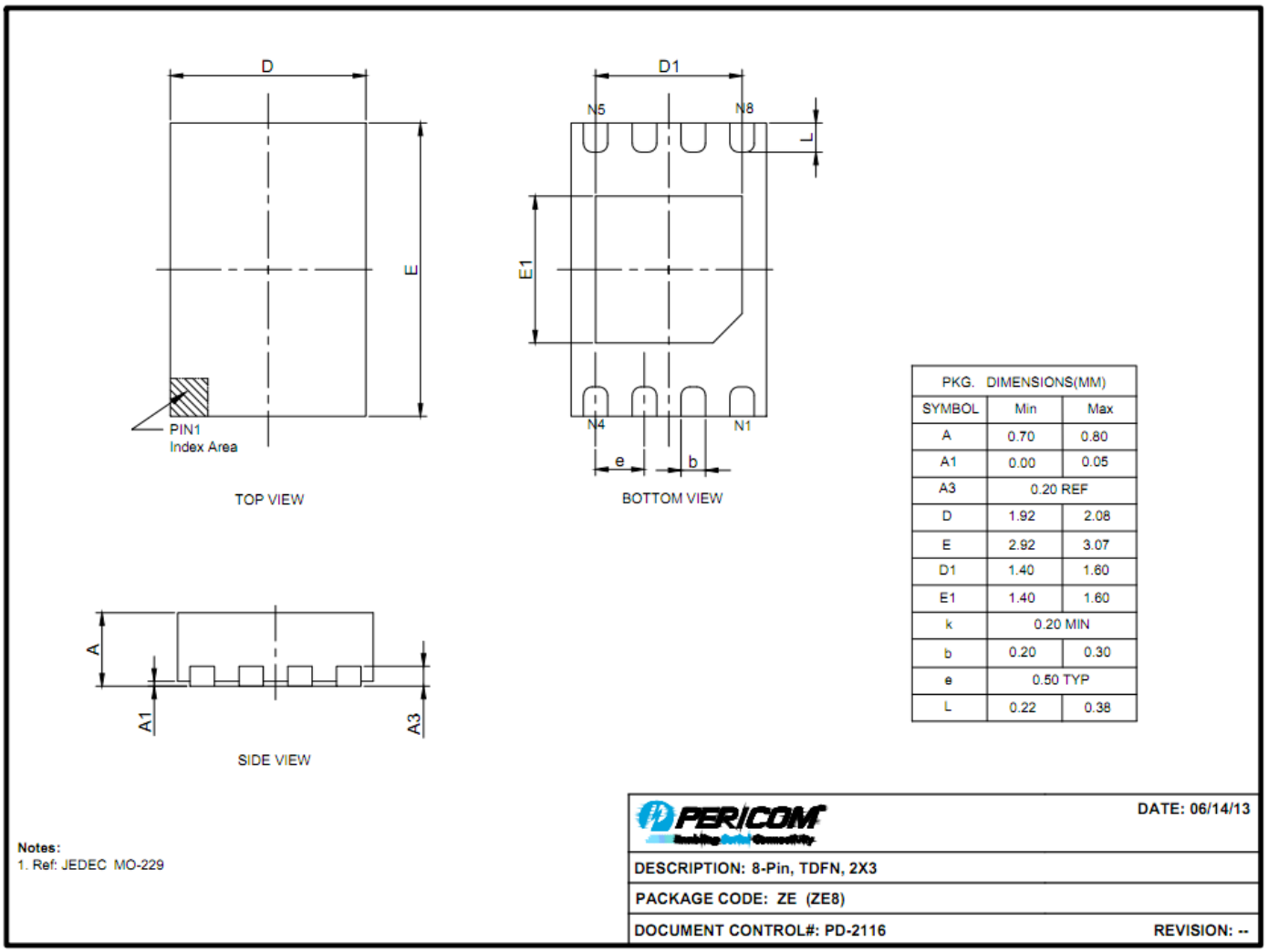
PERICOM Enabling Serial Connectivity — DATE: 04/14/18

DESCRIPTION: 8-Pin, Mini Small Outline Package, MSOP

PACKAGE CODE: U (U8)

DOCUMENT CONTROL #: PD-1261 — REVISION: F

8-TDFN (ZE)



PKG. DIMENSIONS(MM)		
SYMBOL	Min	Max
A	0.70	0.80
A1	0.00	0.05
A3	0.20 REF	
D	1.92	2.08
E	2.92	3.07
D1	1.40	1.60
E1	1.40	1.60
k	0.20 MIN	
b	0.20	0.30
e	0.50 TYP	
L	0.22	0.38

Notes:
1. Ref: JEDEC MO-229

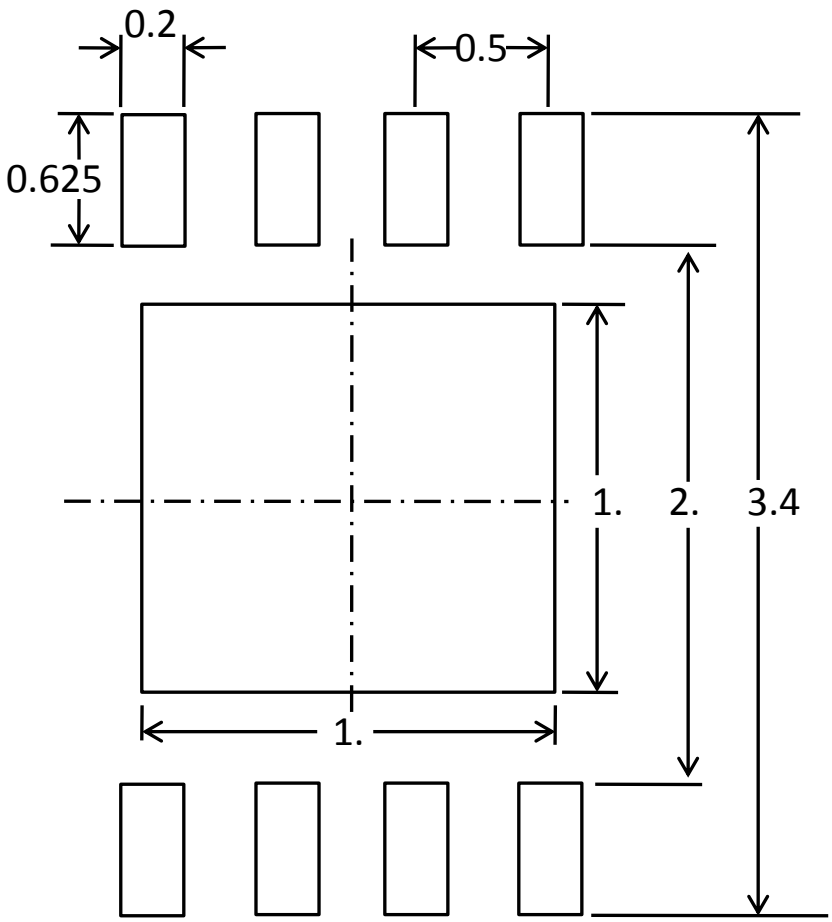
PERICOM Semiconductor Corporation — DATE: 06/14/13

DESCRIPTION: 8-Pin, TDFN, 2X3

PACKAGE CODE: ZE (ZE8)

DOCUMENT CONTROL#: PD-2116 REVISION: --

Recommended Land pattern for TDFN2*3-8L



Note:All linear dimensions are in millimeters

For latest package info.

please check: http://www.diodes.com/design/support/packaging/pericom-packaging/packaging-mechanicals-and-thermal-characteristics/

Ordering Information

Part Number	Package Code	Package
PI6ULS5V9517BUEX	U	8-pin, Mini Small Outline Package (MSOP)
PI6ULS5V9517BZEEX	ZE	8-pin,2x3 (TDFN)

Notes:

1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
2. See http://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Thermal characteristics can be found on the company web site at www.diodes.com/design/support/packaging/
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X suffix = Tape/Reel

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